

High Quality Opto- and Fingerprint-Sensors

Conventional Package



Lithoglas Package

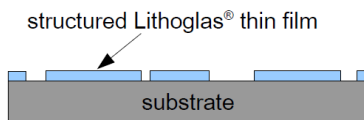


Lithoglas[®] Thin Film Passivation

- Enhanced optical performance (very thin glass, no glue)
- Highly precise structuring by lithography
- Excellent manufacturing yields
by e.g. avoiding thin wafer handling, glue processing, wafer thinning on glue layer, dicing through glass substrate, and more
- Small COB device with high reliability

Optical Performance • High Yield • Tight Tolerances • Reliability

Design Rules:



typ. application: *Surface Passivation
Moisture Barrier
Anodic Bond Layer*

Coating Material
Film Thickness
Thermal Expansion
Optical transmission
Deposition Temperature
Conformal Coating
Structuring Method
Aspect Ratio
Side Wall Angle
Wafer Formats

Borosilicate Glass
 $\geq 0.1 \mu\text{m}, \leq 20 \mu\text{m}$
 $\sim 3 \text{ ppm/K}$
ca. 300 nm to 3000 nm
 $\leq 80^\circ\text{C}$
no
Lift-Off / Shadow Mask / Etching
 ≤ 1 (for Lift-Off)
 $\sim 60^\circ$
SEMI Std. 100 mm, 150 mm, 200 mm dia.